

Electronic Patent Application Fee Transmittal

Application Number:	10595424			
Filing Date:	18-Apr-2006			
Title of Invention:	Semiconductor chip mounted interposer, semiconductor device, semiconductor chip interposer fabrication method, bare chip mounted interposer, and interposer sheet			
First Named Inventor/Applicant Name:	Moriyoshi Nakashima			
Filer:	Mark D. Saralino/Christine Arndt			
Attorney Docket Number:	KOMOP0113US			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120